**D OR N PACKAGE** (TOP VIEW)

G

ΗП 2

Π

NC [ 3

> I 4

 $\Sigma EVEN$ [] 5

Σ ODD

GND

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UVCC 14

13 🛛 F

10 🛛 C

9 **П** В

ΠА 8

ΠD

12 ΠЕ

11

- Generate Either Odd or Even Parity for Nine **Data Lines**
- Cascadable for n-Bit Parity
- Can Be Used to Upgrade Existing Systems **Using MSI Parity Circuits**
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs

#### description

These universal 9-bit parity generators/checkers

utilize advanced Schottky high-performance

NC - No internal connection

6

7

circuitry and feature odd ( $\Sigma$  ODD) and even ( $\Sigma$  EVEN) outputs to facilitate operation of either odd- or even-parity applications. The word-length capability is easily expanded by cascading.

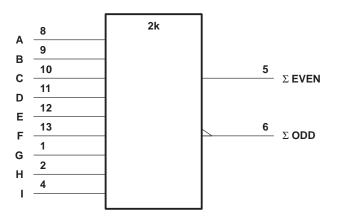
These devices can be used to upgrade the performance of most systems utilizing the SN74ALS180 and SN74AS180 parity generators/checkers. Although the SN74ALS280 and SN74AS280 are implemented without expander inputs, the corresponding function is provided by the availability of an input (I) at terminal 4 and the absence of any internal connection at terminal 3. This permits the SN74ALS280 and SN74AS280 to be substituted for the SN74ALS180 and SN74AS180 in existing designs to produce an identical function even if the devices are mixed with existing SN74ALS180 and SN74AS180 devices.

All SN74AS280 inputs are buffered to lower the drive requirements.

The SN74ALS280 and SN74AS280 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE										
NO. OF INPUTS	OUTF	PUTS								
A – I THAT ARE HIGH	$\Sigma$ EVEN	$\Sigma$ ODD								
0, 2, 4, 6, 8	Н	L								
1, 3, 5, 7, 9	L	Н								

### logic symbol<sup>†</sup>



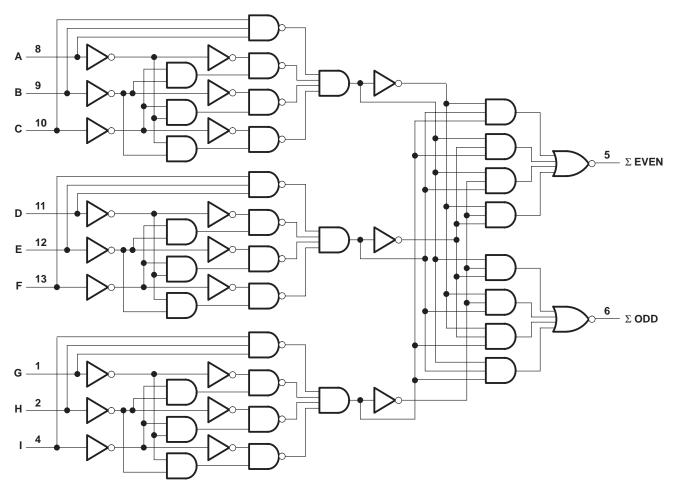
<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub>	
Input voltage, V <sub>I</sub>	
Operating free-air temperature range, T <sub>A</sub> : SN74ALS280	0°C to 70°C
Storage temperature range	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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### recommended operating conditions

		SN	74ALS2	80	
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
ЮН	High-level output current			-2.6	mA
IOL	Low-level output current			24	mA
TA	Operating free-air temperature	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN	74ALS2	80	
PARAMETER	TEST CON	MIN	TYP†	MAX	UNIT	
VIK	V <sub>CC</sub> = 4.5 V,	l <sub>l</sub> = – 18 mA			-1.5	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}, \qquad I_{OH} = -0.4 \text{ mA}$		V <sub>CC</sub> -2	2		N/
VOH	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -2.6 mA	2.4	3.3		V
		I <sub>OL</sub> = 12 mA		0.25	0.4	V
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 24 mA		0.35	0.5	V
li	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1	mA
Ιн	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20	μΑ
١ <sub>IL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.1	mA
IO‡	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	mA
Icc	V <sub>CC</sub> = 5.5 V			10	16	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . <sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I<sub>OS</sub>.

### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 V \text{ to } 5.5 V,$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = \text{MIN to MAX\$}$ SN74ALS280		UNIT
			MIN	MAX	
<sup>t</sup> PLH	A		3	20	
<sup>t</sup> PHL	Any	$\Sigma$ EVEN	3	20	ns
<sup>t</sup> PLH	4.004	Σ ODD	3	20	-
<sup>t</sup> PHL	Any	2 000	4	22	ns

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>1</sub>	7 V
Operating free-air temperature range, T <sub>A</sub> : SN74AS280	0°C to 70°C
Storage temperature range	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN	174AS28	0	
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
IOH	High-level output current			-2	mA
IOL	Low-level output current			20	mA
TA	Operating free-air temperature	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN74AS2				
PARAMETER	TEST CON	MIN TYP <sup>‡</sup> MA		TEST CONDITIONS MIN TY		MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	l <sub>l</sub> = – 18 mA		-1.5	V		
VOH	$V_{CC} = 4.5 V$ to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2		V		
V <sub>OL</sub>	$V_{CC} = 4.5 V,$	I <sub>OL</sub> = 20 mA	0.35	0.5	V		
Ц	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V		0.1	mA		
ЧΗ	V <sub>CC</sub> = 5.5 V,	Vj = 2.7 V		20	μΑ		
Ι <sub>ΙL</sub>	V <sub>CC</sub> = 5.5 V,	$V_I = 0.4 V$		-0.5	mA		
۱ <sub>0</sub> §	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.25 V	-30	-112	mA		
ICC	$V_{CC} = 5.5 V$		25	35	mA		

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> =  $25^{\circ}$ C.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

### switching characteristics (see Figure 1)

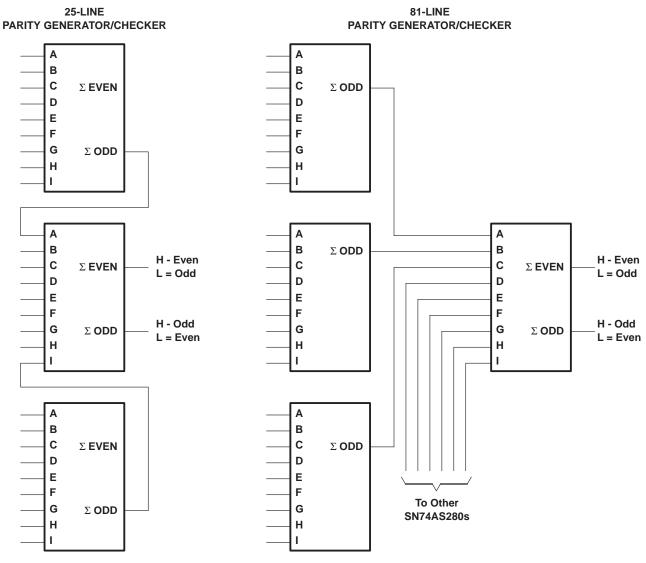
PARAMETER	FROM (INPUT)	то (оитрит)	$R_L = 500 \Omega$ $T_A = MIN t$	$V_{CC} = 4.5 V \text{ to } 5.5 V,$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = \text{MIN to MAX}$ SN74AS280		
			MIN	MAX		
<sup>t</sup> PLH	A		3	12		
<sup>t</sup> PHL	Any	$\Sigma$ EVEN	3	11	ns	
<sup>t</sup> PLH	4.01/	Σ ΟDD	3	12		
<sup>t</sup> PHL	Any	2 000	3	11.5	ns	

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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**APPLICATION INFORMATION** 



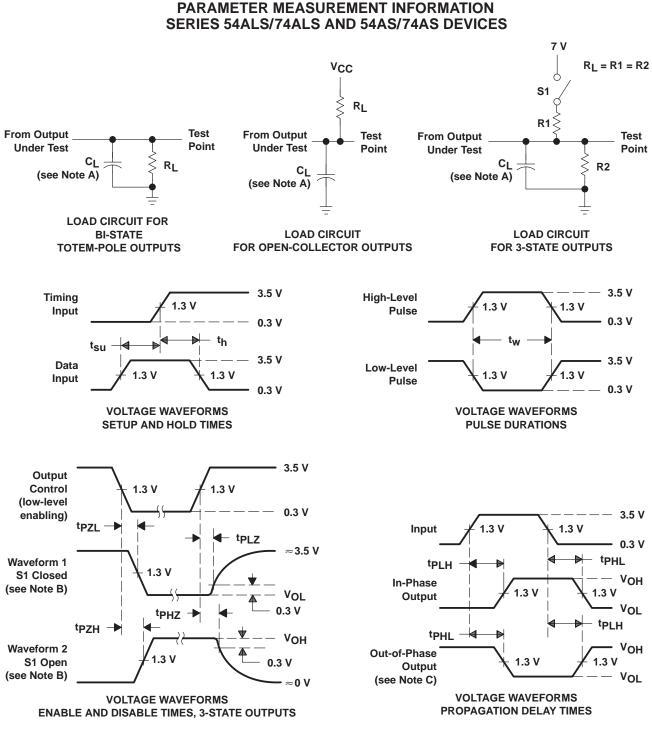
Three SN74ALS280/SN74AS280 devices can be used to implement a 25-line parity generator/ checker.

As an alternative, the  $\Sigma$  ODD outputs of two or three parity generators/checkers can be decoded with a 2-input ('AS86A or 'ALS86) exclusive-OR gate for 18- or 27-line parity applications.

Longer word lengths can be implemented by cascading SN74ALS280/SN74AS280 devices. Parity can be generated for word lengths up to 81 bits.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- . When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz, t<sub>f</sub> = t<sub>f</sub> = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

#### Figure 1. Load Circuits and Voltage Waveforms



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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ALS280DR	NRND	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS280DRE4	NRND	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS280DRG4	NRND	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS280N	NRND	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS280N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74ALS280NE4	NRND	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS280D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS280DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS280DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS280N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS280N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74AS280NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS280NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS280NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS280NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS280DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS280NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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# PACKAGE MATERIALS INFORMATION

10-Feb-2010



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS280DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74AS280NSR	SO	NS	14	2000	346.0	346.0	33.0

## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



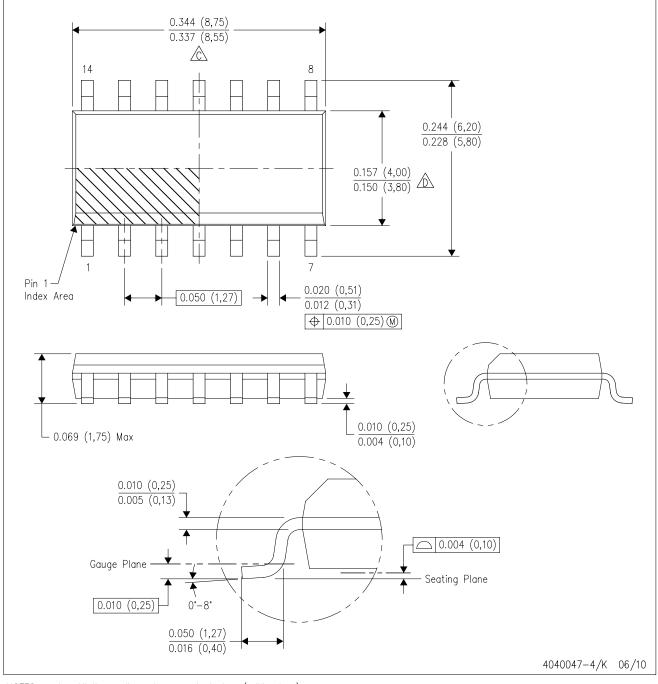
NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



### MECHANICAL DATA

### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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